

(19) World Intellectual Property
Organization
International Bureau



(43) International Publication Date
28 April 2005 (28.04.2005)

PCT

(10) International Publication Number
WO 2005/038915 A1

(51) International Patent Classification⁷: **H01L 23/433**,
23/495, 23/31

(21) International Application Number:
PCT/IB2004/052097

(22) International Filing Date: 14 October 2004 (14.10.2004)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
60/512,561 17 October 2003 (17.10.2003) US

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(81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

(84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

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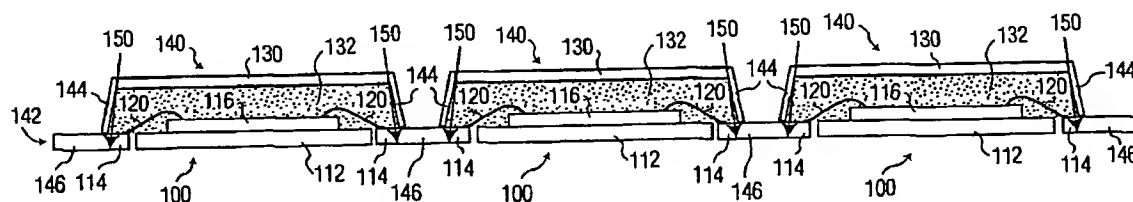
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- as to the applicant's entitlement to claim the priority of the earlier application (Rule 4.17(iii)) for all designations

Published:

- with international search report
- before the expiration of the time limit for amending the claims and to be republished in the event of receipt of amendments

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(54) Title: **METHOD FOR PROVIDING DOUBLE-SIDED COOLING OF LEADFRAME-BASED WIRE-BONDED ELECTRONIC PACKAGES AND DEVICE PRODUCED THEREBY**



(57) Abstract: A method and apparatus for providing double-sided cooling of leadframe-based wire-bonded electronic packages. The method includes the steps of: positioning a plurality of heatslug members (140) over a corresponding plurality of electronic packages (100) formed on a leadframe strip (142), wherein each of the heatslug members includes a heatslug (130) and a plurality of legs (144) for supporting the heatslug over a respective one of the electronic packages; introducing a molding compound (132) of legs (144) for supporting the heatslug over a respective one of the electronic packages; curing the molding compound; and cutting the heatslug members and separating the electronic packages (100) from the leadframe strip, such that each electronic package includes a heatslug for cooling a first side of the electronic package.

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